

April 1992 Revised May 2005

74ABT16245

16-Bit Transceiver with 3-STATE Outputs

General Description

The ABT16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. Each byte has separate control inputs which can be shorted together for full 16-bit operation. The T/R inputs determine the direction of data flow through the device. The $\overline{\text{OE}}$ inputs disable both the A and B ports by placing them in a high impedance state.

Features

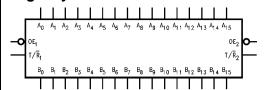
- Bidirectional non-inverting buffers
- Separate control logic for each byte
- 16-bit version of the ABT245
- A and B output sink capability of 64 mA, source capability of 32 mA
- Guaranteed output skew
- Guaranteed multiple output switching specifications
- Output switching specified for both 50 pF and 250 pF loads
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Non-destructive hot insertion capability

Ordering Code:

Order Number	Package Number	Package Description
74ABT16245CSSC	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74ABT16245CMTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

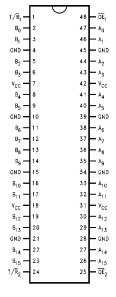
Logic Symbol



Pin Descriptions

Pin Names	Description			
OEn	Output Enable Input (Active LOW)			
T/R _n	Transmit/Receive Input			
A ₀ -A ₁₅	Side A Inputs/Outputs			
B ₀ –B ₁₅	Side B Inputs/Outputs			

Connection Diagram



Truth Tables

Inp	outs	Outputs
OE ₁	T/R ₁	
L	L	Bus B ₀ -B ₇ Data to Bus A ₀ -A ₇
L	Н	Bus A ₀ -A ₇ Data to Bus B ₀ -B ₇
Н	Х	HIGH-Z State on A ₀ –A ₇ , B ₀ –B ₇

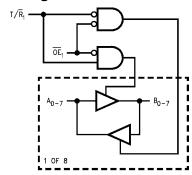
Inputs		Outputs
OE ₂	T/R ₂	
L	L	Bus B ₈ –B ₁₅ Data to Bus A ₈ –A ₁₅
L	Н	Bus A ₈ -A ₁₅ Data to Bus B ₈ -B ₁₅
Н	X	HIGH-Z State on A ₈ -A ₁₅ , B ₈ -B ₁₅

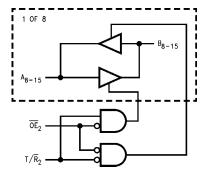
- H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = High Impedance

Functional Description

The ABT16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation.

Logic Diagrams





Absolute Maximum Ratings(Note 1)

-65°C to +150°C Storage Temperature -55°C to +125°C Ambient Temperature under Bias

Junction Temperature under Bias -55°C to +150°C -0.5V to +7.0V

V_{CC} Pin Potential to Ground Pin

Input Voltage (Note 2) -0.5V to +7.0VInput Current (Note 2) -30 mA to +5.0 mA

Voltage Applied to Any Output

in the Disabled or

Power-Off State -0.5V to 5.5Vin the HIGH State -0.5V to V_{CC}

Current Applied to Output

in LOW State (Max) twice the rated I_{OL} (mA) DC Latchup Source Current -500 mA

Over Voltage Latchup (I/O) 10V

Recommended Operating Conditions

-40°C to +85°C Free Air Ambient Temperature Supply Voltage +4.5V to +5.5V

Minimum Input Edge Rate ($\Delta V/\Delta t$)

50 mV/ns Data Input 20 mV/ns Enable Input

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Paran	neter	Min	Тур	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage		2.0			V		Recognized HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized LOW Signal
V _{CD}	Input Clamp Diode Vo	Itage			-1.2	V	Min	$I_{IN} = -18 \text{ mA } (\overline{OE}_n, T/\overline{R}_n)$
V _{OH}	Output HIGH Voltage		2.5			V	Min	$I_{OH} = -3 \text{ mA } (A_n, B_n)$
			2.0			V	Min	$I_{OH} = -32 \text{ mA } (A_n, B_n)$
V _{OL}	Output LOW Voltage				0.55	V	Min	$I_{OL} = 64 \text{ mA } (A_n, B_n)$
I _{IH}	Input HIGH Current				1	μА	Max	$V_{IN} = 2.7V (\overline{OE}_n, T/\overline{R}_n) (Note 3)$
					1			$V_{IN} = V_{CC} (\overline{OE}_n, T/\overline{R}_n)$
I _{BVI}	Input HIGH Current Br	eakdown Test			7	μА	Max	$V_{IN} = 7.0V (\overline{OE}_n, T/\overline{R}_n)$
I _{BVIT}	Input HIGH Current Br	reakdown Test (I/O)			100	μА	Max	$V_{IN} = 5.5V (A_n, B_n)$
I _{IL}	Input LOW Current				-1	μА	Max	$V_{IN} = 0.5V (\overline{OE}_n, T/\overline{R}_n) (Note 3)$
					-1			$V_{IN} = 0.0V (\overline{OE}_n, T/\overline{R}_n)$
V _{ID}	Input Leakage Test		4.75			V	0.0	$I_{ID} = 1.9 \mu A (\overline{OE}_n, T/\overline{R}_n)$
								All Other Pins Grounded
I _{IH} + I _{OZH}	Output Leakage Curre	nt			10	μА	0 – 5.5V	$V_{OUT} = 2.7V (A_n, B_n); \overline{OE} = 2.0V$
$I_{IL} + I_{OZL}$	Output Leakage Curre				-10	μА	0 - 5.5V	$V_{OUT} = 0.5V (A_n, B_n); \overline{OE} = 2.0V$
I _{OS}	Output Short-Circuit C		-100		-275	mA	Max	$V_{OUT} = 0.0V (A_n, B_n)$
I _{CEX}	Output HIGH Leakage	Current			50	μА	Max	$V_{OUT} = V_{CC} (A_n, B_n)$
I_{ZZ}	Bus Drainage Test	<u> </u>			100	μА	0.0	$V_{OUT} = 5.50V (A_n, B_n);$
								All Others GND
I _{CCH}	Power Supply Current				100	μА	Max	All Outputs HIGH
I _{CCL}	Power Supply Current				60	mA	Max	All Outputs LOW
I _{CCZ}	Power Supply Current				100	μΑ	Max	$\overline{OE}_n = V_{CC}$, $T/\overline{R}_n = GND$ or V_{CC}
								All others at V _{CC} or GND
I _{CCT}	Additional I _{CC} /Input	Outputs Enabled			2.5	mA		V _I = V _{CC} - 2.1V
		Outputs 3-STATE			2.5	mA	Max	\overline{OE}_n , $T/\overline{R}_n V_I = V_{CC} - 2.1V$
		Outputs 3-STATE			50	μΑ		Data Input V _I = V _{CC} - 2.1V
								All others at V _{CC} or GND
I _{CCD}	Dynamic I _{CC}	No Load				mA/	Max	Outputs OPEN
	(Note 3)				0.1	MHz		$\overline{OE}_n = GND, T/\overline{R}_n = GND \text{ or } V_{CC}$
								One Bit Toggling, 50% Duty Cycle

Note 3: Guaranteed, but not tested.

DC Extended Electrical Characteristics

Symbol	Parameter	Min	Тур	Max	Units	V _{CC}	Conditions	
Cymbol	1 diameter		iyp	WILL	Oilita	• 66	$C_L = 50 \text{ pF}; R_L = 500\Omega$	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}		0.5	0.9	V	5.0	T _A = 25°C (Note 4)	
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	-1.4	-1.0		V	5.0	T _A = 25°C (Note 4)	
V _{OHV}	Minimum HIGH Level Dynamic Output Voltage	2.5	3.0		V	5.0	T _A = 25°C (Note 5)	
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	2.0	1.4		V	5.0	T _A = 25°C (Note 5)	
V _{ILD}	Maximum LOW Level Dynamic Input Voltage		1.2	0.8	V	5.0	T _A = 25°C (Note 6)	

Note 4: Max number of outputs defined as (n). n - 1 data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.

Note 5: Max number of outputs defined as (n). n - 1 data inputs are driven 0V to 3V. One output HIGH. Guaranteed, but not tested.

Note 6: Max number of data inputs (n) switching. n – 1 inputs switching 0V to 3V. Input-under-test switching: 3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}). Guaranteed, but not tested.

AC Electrical Characteristics

Symbol	Parameter	$T_A = +25^{\circ}C$ $V_{CC} = +5V$ $C_L = 50 \text{ pF}$		$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$ $V_{CC} = 4.5V - 5.5V$ $C_L = 50 \text{ pF}$		$T_A = -40^{\circ}\text{C to} + 85^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ $C_L = 50 \text{ pF}$		Units	
		Min	Тур	Max	Min	Max	Min	Max	
t _{PLH}	Propagation	1.0	2.4	3.9	0.5	4.5	1.0	3.9	20
t _{PHL}	Delay Data to Outputs	1.0	2.8	3.9	0.5	5.2	1.0	3.9	ns
t _{PZH}	Output Enable	1.5	3.6	6.3	0.8	6.4	1.5	6.3	ns
t _{PZL}	Time	1.5	3.7	6.3	0.9	6.9	1.5	6.3	115
t _{PHZ}	Output Disable	1.3	4.6	6.9	1.3	6.9	1.3	6.9	20
t _{PLZ}	Time	1.3	3.7	6.9	1.0	6.9	1.3	6.9	ns

Extended AC Electrical Characteristics

Symbol	Parameter	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ $C_L = 50 \text{ pF}$ 16 Outputs Switching (Note 7)		$T_A = -40$ °C to +85°C $V_{CC} = 4.5V-5.5V$ $C_L = 250$ pF 1 Output Switching (Note 8)		$T_A = -40^{\circ}\text{C to} + 85^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ $C_L = 250 \text{ pF}$ 16 Outputs Switching (Note 9)		Units	
		Min	Тур	Max	Min	Max	Min	Max	
f _{TOGGLE}	Maximum Toggle Frequency		100						MHz
t _{PLH}	Propagation Delay	1.5		5.0	1.5	6.0	2.5	8.0	ns
t _{PHL}	Data to Outputs	1.5		5.3	1.5	6.0	2.5	8.0	115
t _{PZH}	Output Enable	1.5		6.5	2.5	8.2	2.5	10.0	ns
t_{PZL}	Time	1.5		6.5	2.5	8.2	2.5	9.0	115
t _{PHZ}	Output Disable	1.0		6.9	(Note 10)		(Note 10)		ne
t _{PLZ}	Time	1.0		6.9					ns

Note 7: This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.).

Note 8: This specification is guaranteed but not tested. The limits represent propagation delay with 250 pF load capacitors in place of the 50 pF load capacitors in the standard AC load. This specification pertains to single output switching only.

Note 9: This specification is guaranteed but not tested. The limits represent propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.) with 250 pF load capacitors in place of the 50 pF load capacitors in the standard AC load.

 $\textbf{Note 10: } 3\text{-STATE delay are dominated by the RC network (500\Omega, 250 pF) on the output and have been excluded from the datasheet.$

Skew

Symbol	Parameter	T _A = -40°C to +85°C V _{CC} = 4.5V-5.5V C _L = 50 pF 16 Outputs Switching (Note 11) Max	$T_A = -40$ °C to +85°C $V_{CC} = 4.5V-5.5V$ $C_L = 250$ pF 16 Outputs Switching (Note 12)	Units	
t _{OSHL} (Note 13)	Pin to Pin Skew HL Transitions	1.3	1.5	ns	
t _{OSLH} (Note 13)	Pin to Pin Skew LH Transitions	1.3	1.5	ns	
t _{PS} (Note 14)	Duty Cycle LH–HL Skew	1.5	2.0	ns	
t _{OST} (Note 13)	Pin to Pin Skew LH/HL Transitions	1.7	2.5	ns	
t _{PV} (Note 15)	Device to Device Skew LH/HL Transitions	2.0	3.0	ns	

Note 11: This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.)

Note 12: These specifications guaranteed but not tested. The limits represent propagation delays with 250 pF load capacitors in place of the 50 pF load capacitors in the standard AC load.

Note 13: Skew is defined as the absolute value of the difference between the actual propagation delays for any two separate outputs of the same device. The specification applies to any outputs switching HIGH to LOW (toSHL), LOW to HIGH (toSLH), or any combination switching LOW-to-HIGH and/or HIGH-to-LOW (toST). The specification is guaranteed but not tested.

Note 14: This describes the difference between the delay of the LOW-to-HIGH and the HIGH-to-LOW transition on the same pin. It is measured across all the outputs (drivers) on the same chip, the worst (largest delta) number is the guaranteed specification. This specification is guaranteed but not tested.

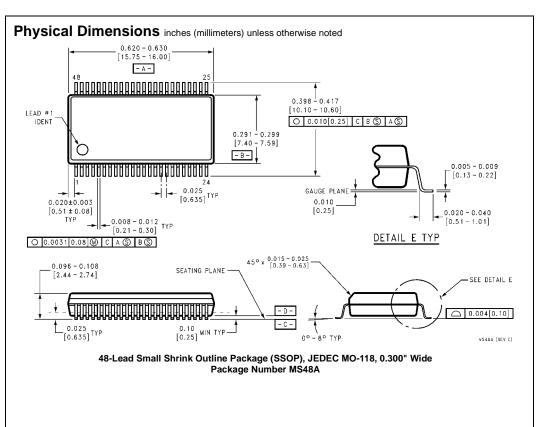
Note 15: Propagation delay variation for a given set of conditions (i.e., temperature and V_{CC}) from device to device. This specification is guaranteed but not tested

Capacitance

Symbol	Parameter	Тур	Units	Conditions T _A = 25°C
C _{IN}	Input Capacitance	5	pF	$V_{CC} = 0.0V (\overline{OE}_n, T/\overline{R}_n)$
C _{I/O} (Note 16)	Output Capacitance	11	pF	$V_{CC} = 5.0V (A_n, B_n)$

Note 16: $C_{I/O}$ is measured at frequency f=1 MHz, per MIL-STD-883, Method 3012.

AC Loading OPEN NEGATIVE PULSE t_{PZL} , t_{PLZ} ALL OTHER 500Ω D.U.T. POSITIVE PULSE 500Ω 10% $V_{M} = 1.5V$ *Includes jig and probe capacitance FIGURE 2. Input Pulse Requirements FIGURE 1. Standard AC Test Load Amplitude Rep. Rate t_W 3.0V 1 MHz 500 ns 2.5 ns 2.5 ns FIGURE 3. Test Input Signal Requirements **AC Waveforms** OUTPUT CONTROL DATA Vm = 1.5V Vm = 1.5V ^tPLH DATA OUT DATA ^t₽ZL OUT ^tPLZ DATA ^tPLH FIGURE 6. Propagation Delay Waveforms for FIGURE 4. 3-STATE Output HIGH **Inverting and Non-Inverting Functions** and LOW Enable and Disable Times Vm = 1.5V CLOCK OR CONTROL Vm = 1.5V DATA IN t_{h(L)} $t_{s(L)}$ ^th(H) Vm = 1.5V $t_{s(H)}$ CLOCK OR CONTROL Vm = 1.5V DATA OUT INPUT $\overline{MR}, \overline{CLR}$ Vm = 1.5V PRE FIGURE 7. Setup Time, Hold Time FIGURE 5. Propagation Delay, **Pulse Width Waveforms** and Recovery Time Waveforms



Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-10±0,10 99 9.30 B.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT LAND PATTERN RECOMMENDATION O.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 0.10±0.05 0.50 0.17-0.27 ♦ 0.13\(\old{\text{0}} \) A B\(\old{\text{S}} \) C\(\old{\text{S}} \) 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS GAGE PLANE 0.25 NOTES A. CONFORMS TO JEDEC REGISTRATION MC-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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